

parent case

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U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MI22-2393PRIORITY SERIAL NO.
09/592,604LIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)APPLICANT
Fernando GonzalezPRIORITY FILING DATE
June 12, 2000PRIORITY GROUP
2818

U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TR	AA	5,298,449	03/94	Kikuchi			
	AB	5,374,564	12/94	Bruel			
	AC	5,855,693	01/99	Murari et al.			
	AD	5,877,070	03/99	Goesle et al.			
	AE	5,882,987	03/99	Srikrishnan			
	AF	5,894,152	04/99	Jaso et al.			
	AG	5,953,622	09/99	Lee et al.			
	AH	6,004,406	12/99	Kobayashi et al.			
	AI	6,309,945 B1	10/01	Sato et al.			
	AJ	6,429,070 B1	08/02	Gonzalez et al.			
	AK	6,384,439 B1	05/02	Walker			
		6,423,992 B2	07/02	Fukuda, et al.			
	AL	5,998,847	12/99	Assaderaghi, et al.			

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AM							
	AN							
	AO							
	AP							
	AQ							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

TR	AR	Göscle, U. et al., "Semiconductor Wafer Bonding: Science, Technology, and Applications", Electrochemical Society Proceedings
		Vol. 97-36, (©1998), pp. 400-425, 436-445.
	AS	

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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